

Application Note No. 049

DECT Transmit - Receiver Switch Using Ultra
Small PIN Diodes

RF & Protection Devices



Never stop thinking

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DECT Transmit - Receiver Switch Using Ultra Small PIN Diodes

Revision History: 2006-10-11, Rev. 2.0

Previous Version: 2000-07-28

Page	Subjects (major changes since last revision)
All	Document layout change

DECT Transmit - Receive Switch Using Ultra Small PIN Diodes

1 DECT Transmit - Receive Switch Using Ultra Small PIN Diodes

This application note covers a redesign of a PIN diode switch introduced in application note No. 007. It uses diodes in SCD80 and SOT343 package, 0603 size SMD components and a 0.25 mm high FR4 printed circuit board.

Advantages

- Small real estate consumption on PCB
- Power consumption in transmit-mode only
- Low component count
- Low cost

Schematic

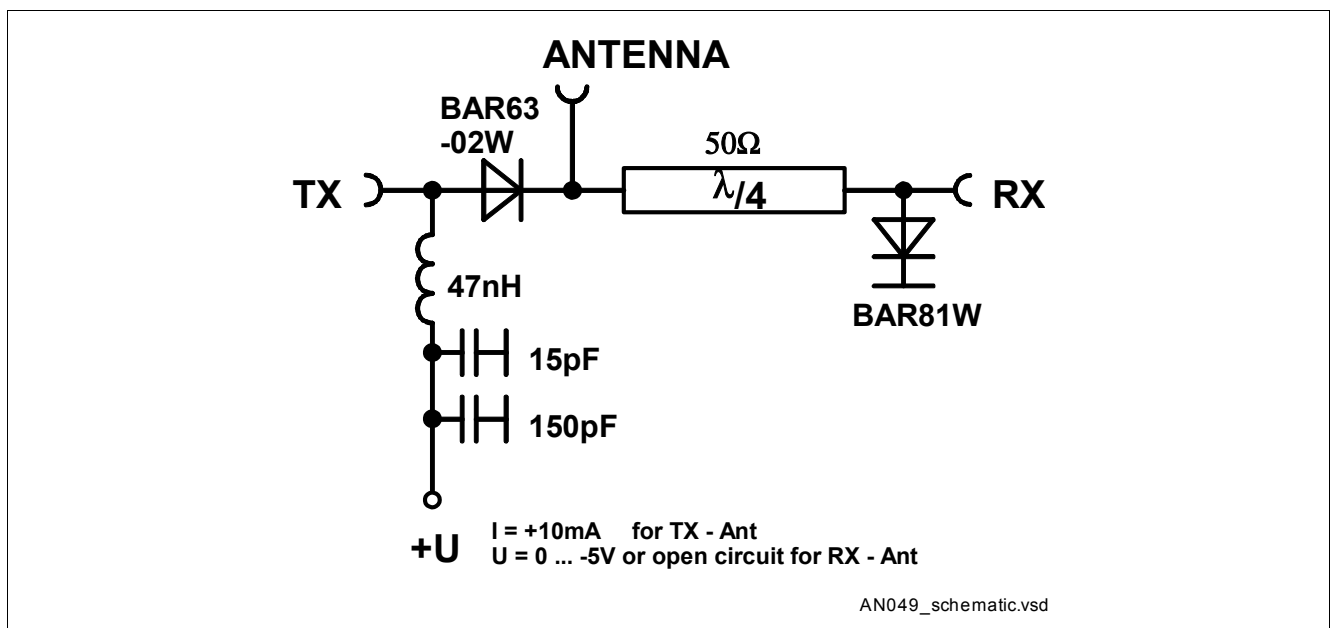


Figure 1 Schematic

Measured Data of Prototype Board

Table 1 Measured data $f = 1.89$ GHz

Transmit-state ($I = +10$ mA at +U-pin)		Receive-state ($U = -3$ V at +U-pin)	
TX-Ant. Loss	0.47 dB	RX-Ant. Loss	0.70 dB
TX-RX Isolation	29.4 dB	TX-RX Isolation	19.8 dB
RX-Ant. Isolation	29.7 dB	TX-Ant. Isolation	18.5 dB

Due to the reduced width of a $50\ \Omega$ line on the thinner PCB material the losses are slightly higher than in application note No. 007. Please note that TX-RX Isolation is improved by 3 dB in transmit-mode and more than 6 dB in receive-mode.

The applied -3 V at the +U control port for the small-signal measurement are not necessary in 'real' operation. If +U is left open circuit in receive-mode, a small reverse bias is generated by the diodes, if there is still an RF signal from the transmitter.

1.1 Harmonic Distortion Measurements

Measurement Setup

TX-Port	1.9 GHz, +27 dBm power, harmonics more than 100 dB down
RX-Port	50 Ω termination
Ant.-Port	Spectrum analyzer
+U-Pin	$I = 5$ mA and $I = 10$ mA

Results

Harmonics referred to TX-Port input level (+27 dBm):

3.8 GHz	-87 dB @ $I = 5$ mA	-92 dB @ $I = 10$ mA
5.7 GHz	> -100 dB @ $I = 5$ mA	> -100dB @ $I = 10$ mA

Note: All ports must be DC-blocked during measurements

Realization

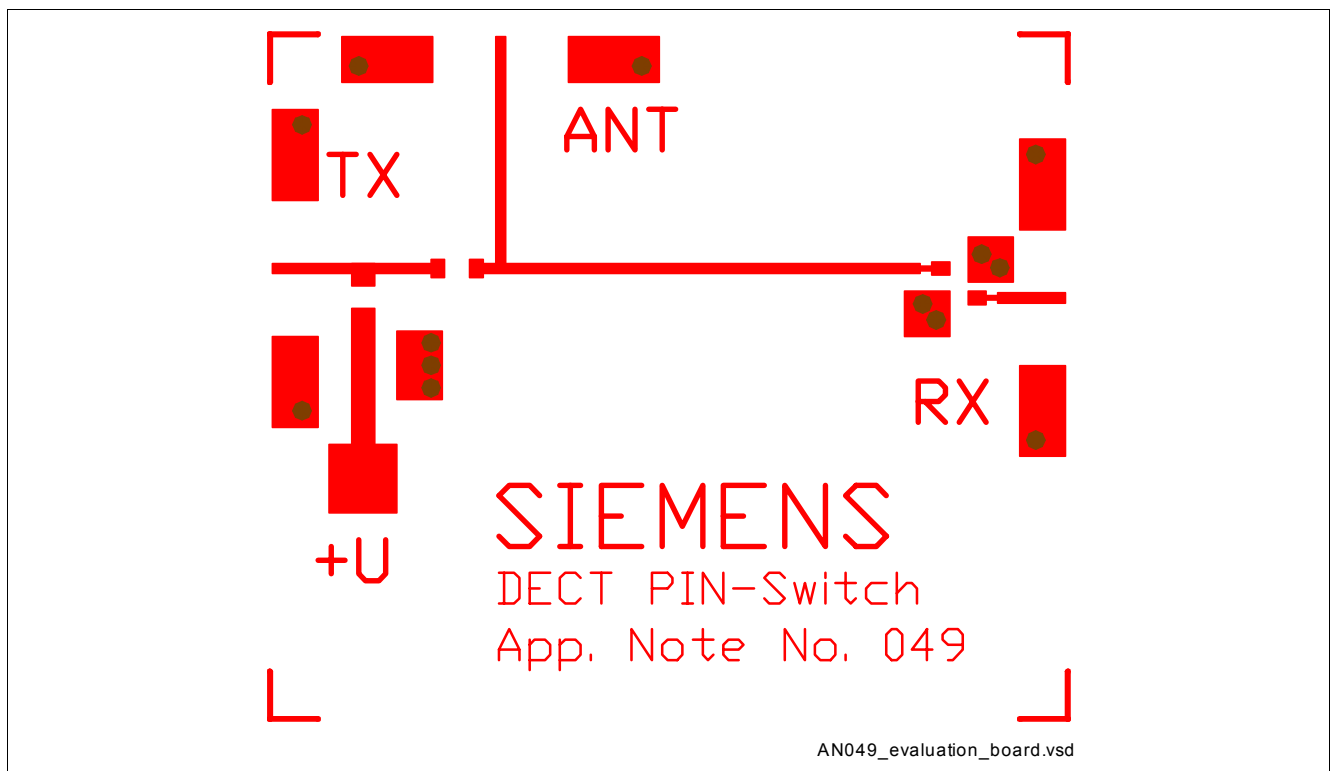


Figure 2 Evaluation Board

Board size: 35 mm x 30 mm, Scale: 3:1

The demo board was made of 0.25 mm FR4 Epoxy material

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Component placement

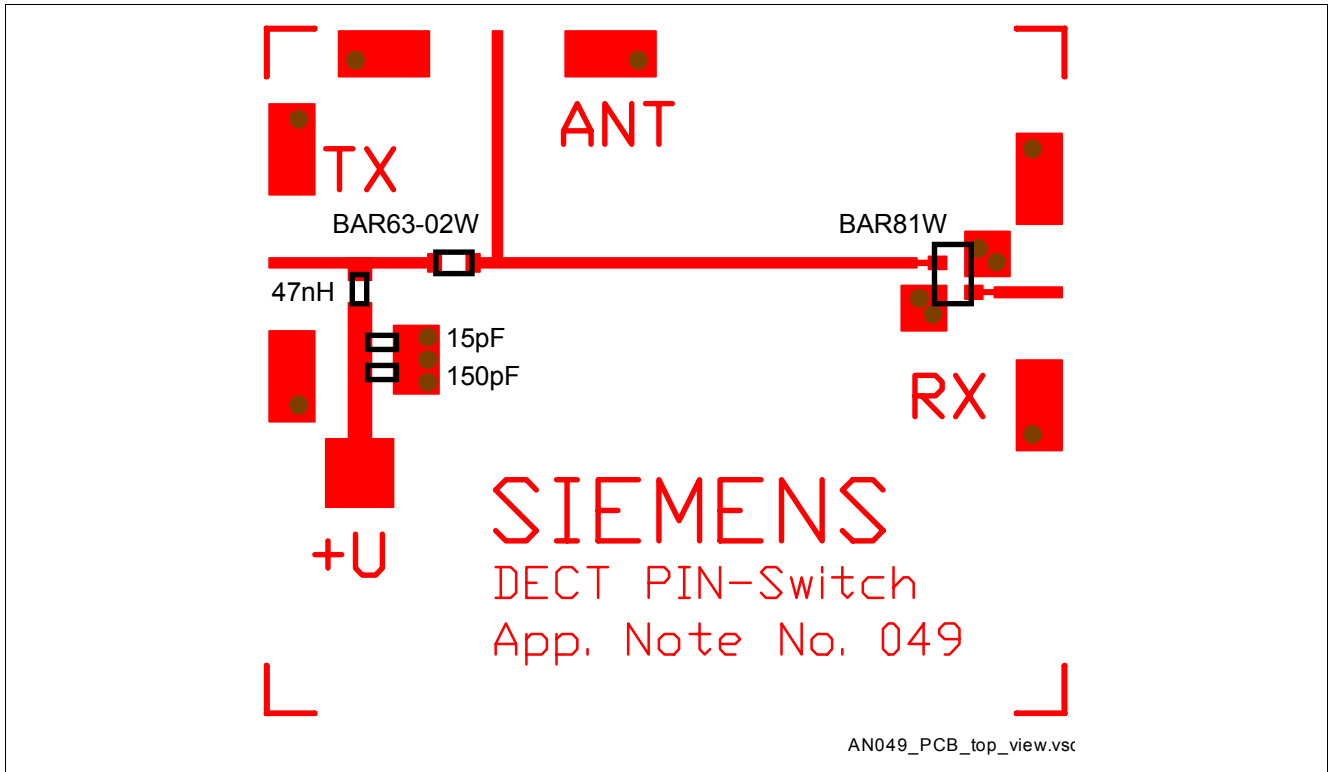


Figure 3 Top view on assembled PCB

Part list

Table 2 Part list

BAR81W	PIN diode	SOT343	Infineon
BAR63-02W	PIN diode	SCD80	Infineon
15 pF	Capacitor	0603	S+M
150 pF	Capacitor	0603	S+M
47 nH	Inductor	0603	S+M
Printed circuit board		FR4, 0.25 mm	Div.

Numeric computation

This circuit was developed using Microwave Harmonica V 7.0. To compute the frequency response of the circuit the freely distributed S-Parameter files of the Infineon diodes were used. For the SMD inductor a simple parallel equivalent circuit was developed.

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```

BLK
STEP 1 43 W1=WAP W2=WM SUB
TRL 43 44 W=WM P=PM SUB
STEP 44 45 W1=WM W2=0.6MM SUB
TRL 45 60 W=0.6MM P=0.4MM SUB
OST 60 W=0.6MM P=0.4MM SUB
CAP 60 0 C=50fF
TWO 60 70 80 B81ON ; BAR81W ON STATE
OST 70 W=0.6MM P=0.4MM SUB
CAP 70 0 C=50fF
TRL 80 81 W=1MM P=1MM SUB
VIA 81 D=0.5MM SUB
TRL 80 82 W=1MM p=1MM SUB
VIA 82 D=0.5MM SUB
TRL 70 71 W=0.6MM P=0.8MM SUB
STEP 71 72 W1=0.6MM W2=WM SUB
TRL 72 73 W=WM P=PM SUB
STEP 73 2 W1=WM W2=W50 SUB
S_ON: 2POR 1 2
END

BLK ; SWITCH IN RECEIVE-MODE: TX-ANT OFF, RX-ANT ON
TRL 1 7 W=W50 P=4MM SUB
TRL 7 10 W=W50 P=3MM SUB
IND 7 8 L=47nH ; Equivalent circuit of
RES 8 0 R=2.0 ; 47nH S+M 0603 SMD inducto:
CAP 7 0 C=140fF ; in parallel resonance
OST 10 W=W50 P=0.6MM SUB
ONE 10 20 B630F ; BAR63-02W OFF STATE
OST 20 W=W50 P=0.6MM SUB
TRL 20 30 W=W50 P=0.54MM SUB
TEE 30 40 50 W1=W50 W2=WAP W3=W50 SUB
TRL 50 2 W=W50 P=10MM SUB
TRL 40 42 W=WAP P=LL SUB
S_OFF 42 75 ; Shunt Diode ON-State
TRL 75 3 W=W50 P=3MM SUB
RXAN: 3POR 1 2 3 ; 1=TX 2=ANT 3=RX
END

```

AN049_simulation_file3.vsd

Figure 6 Simulation file 3

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```

BLK      ; SWITCH IN TRANSMIT-MODE: TX-ANT ON, RX-ANT OFF
TRL      1 7      W=W50    P=4MM      SUB
TRL      7 10     W=W50    P=3MM      SUB
IND      7 8      L=47nH
RES      8 0      R=2.0
CAP      7 0      C=140fF
OST      10      W=W50    P=0.6MM     SUB
ONE      10 20    B63ON
OST      20      W=W50    P=0.6MM     SUB
TRL      20 30    W=W50    P=0.54MM  SUB
TEE      30 40 50 W1=W50   W2=WAP   W3=W50  SUB
TRL      50 2     W=W50    P=10MM   SUB
TRL      40 42    W=WAP     P=LL     SUB
S_ON     42 75
TRL      75 3     W=W50    P=3MM
TXAN:    3POR 1 2 3
END

FREQ
STEP     100MHZ  3GHZ  10MHZ
END

DATA
SUB:     MS H=0.25MM ER=4.4 TAND=0.024 MET1=CU 18UM
B81OF:DUMMY FILE=MU5V00U0.S2P
B81ON:DUMMY FILE=MUV0010M.S2P
B63OF:DUMMY FILE=PT5V00U0.S1P
B63ON:DUMMY FILE=PTV0010M0.S1P
END

```

AN049_simulation_file4.vsd

Figure 7 Simulation file 4

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Computation and measurement results

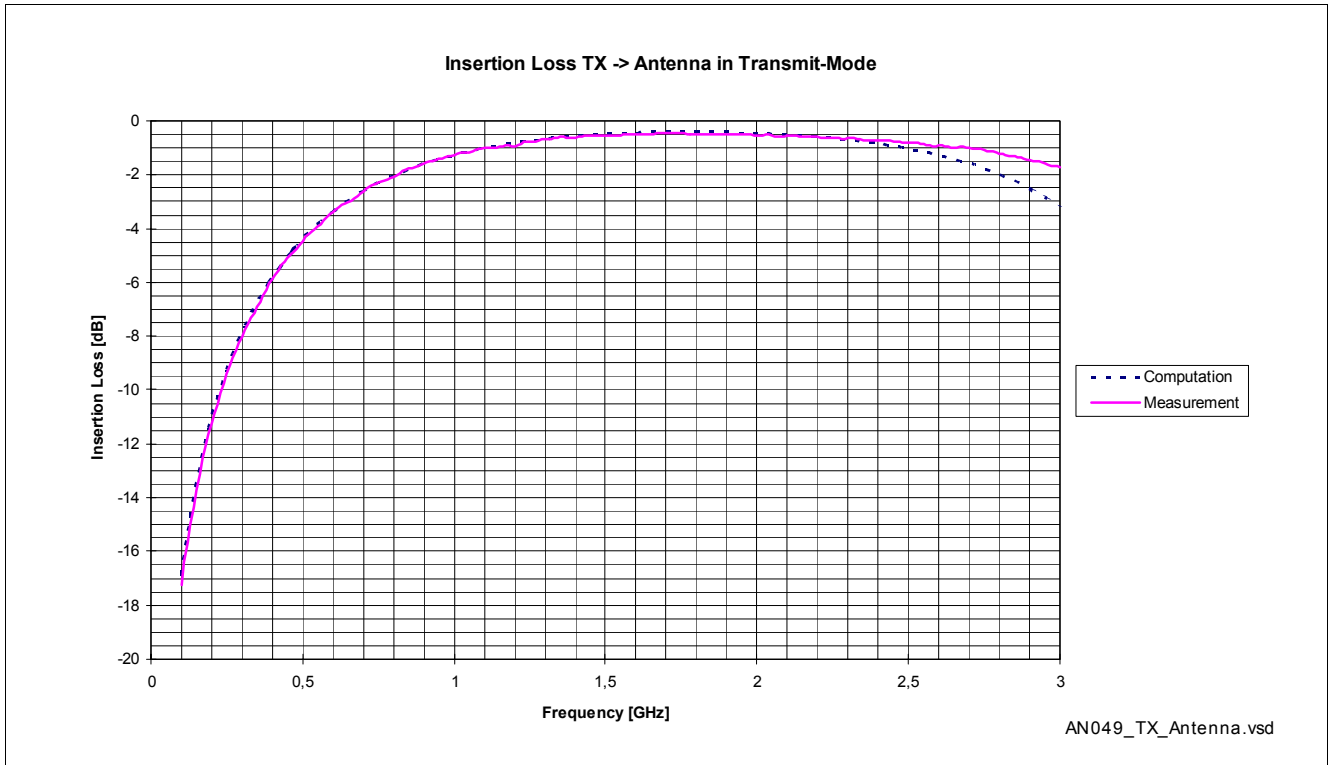


Figure 8 Insertion Loss TX → Antenna in Transmit-Mode

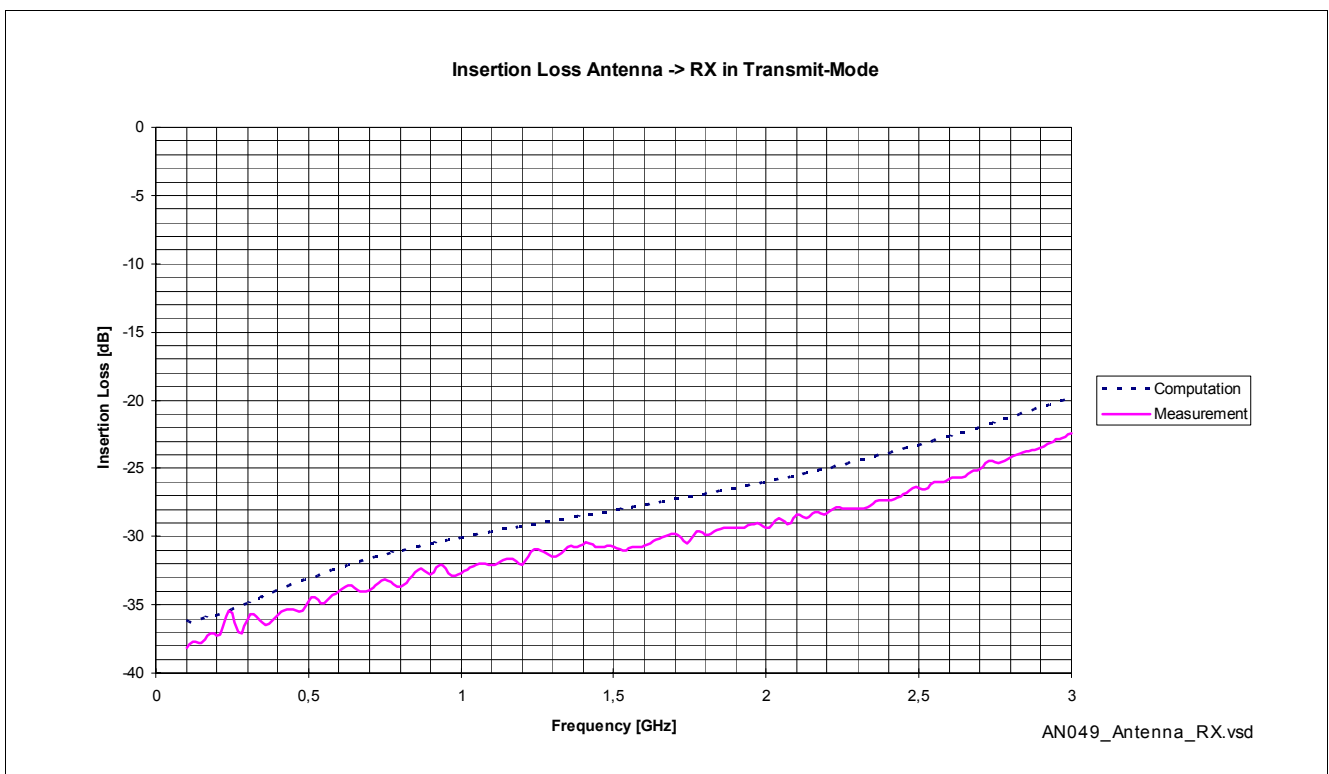


Figure 9 Insertion Loss Antenna → RX in Transmit-Mode

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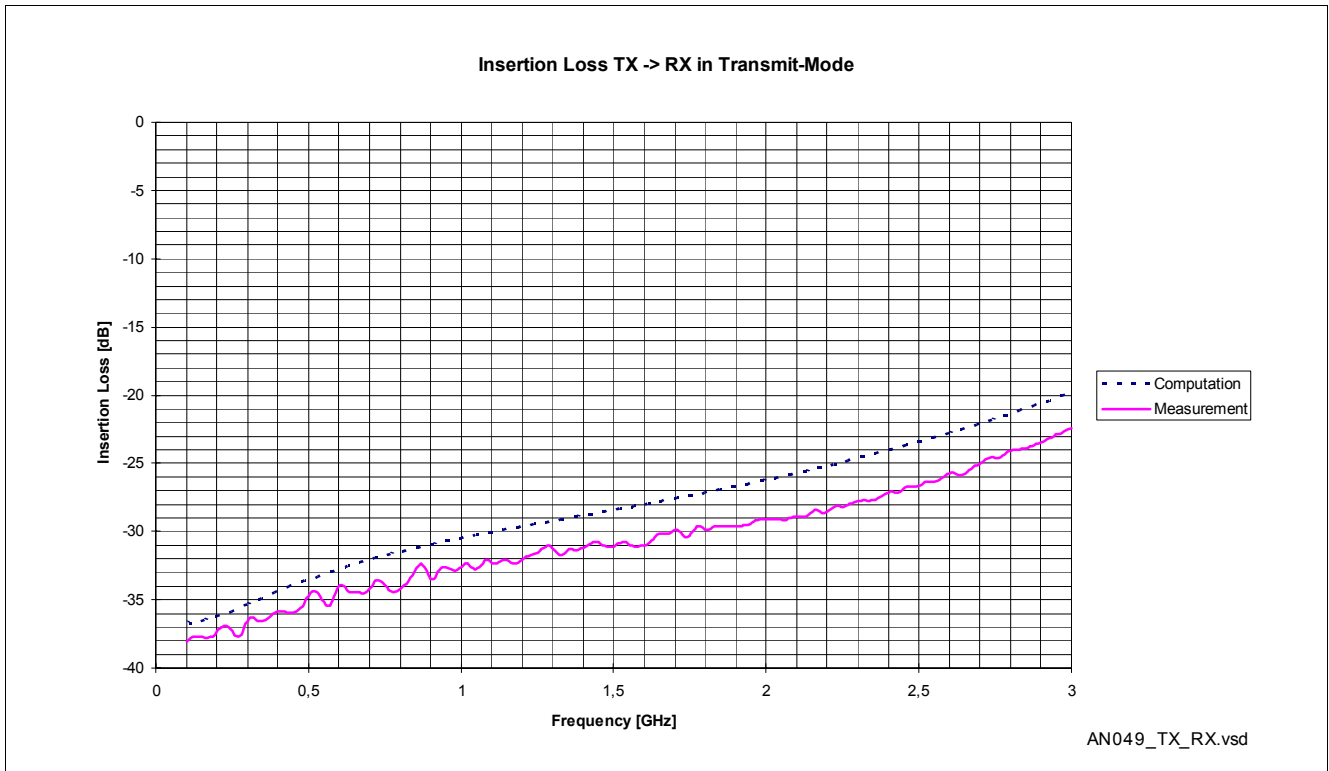


Figure 10 Insertion Loss TX → RX in Tranmit-Mode

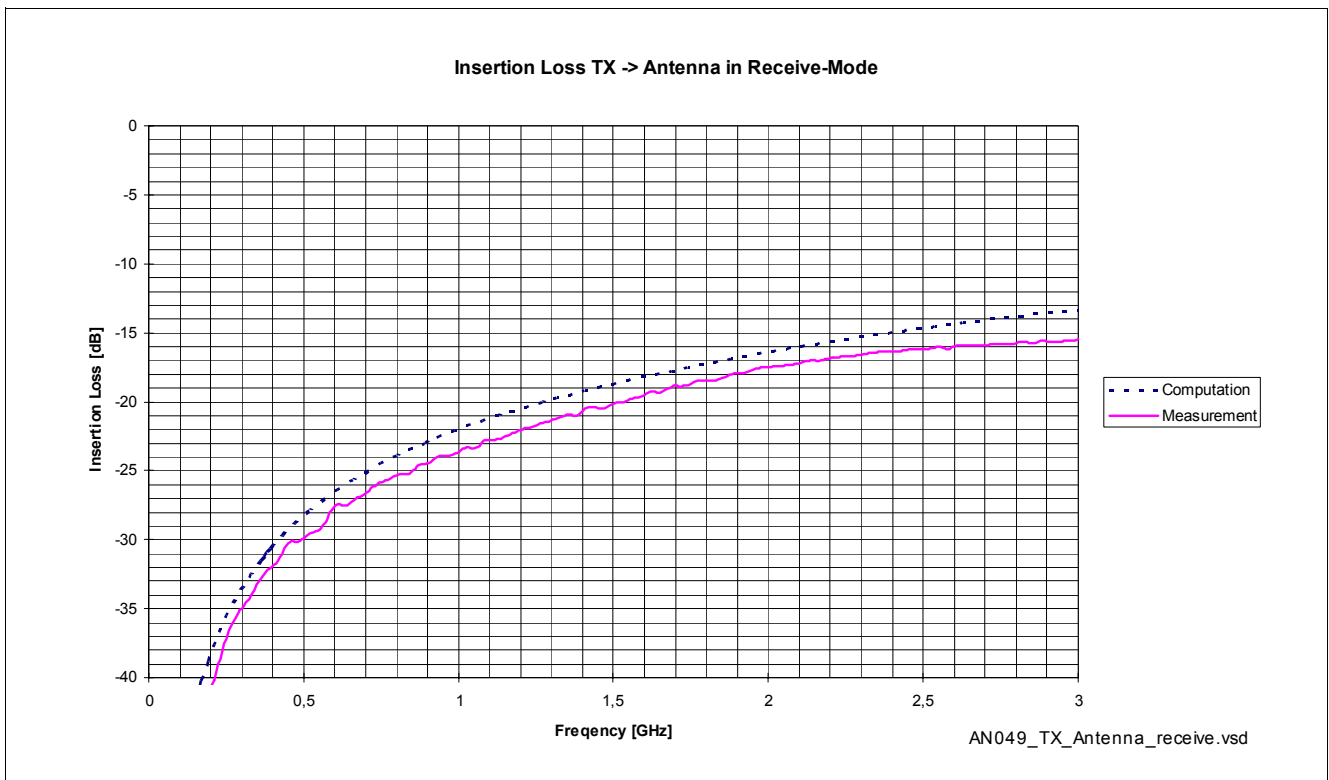


Figure 11 Insertion Loss TX → Antenna in Receive-Mode

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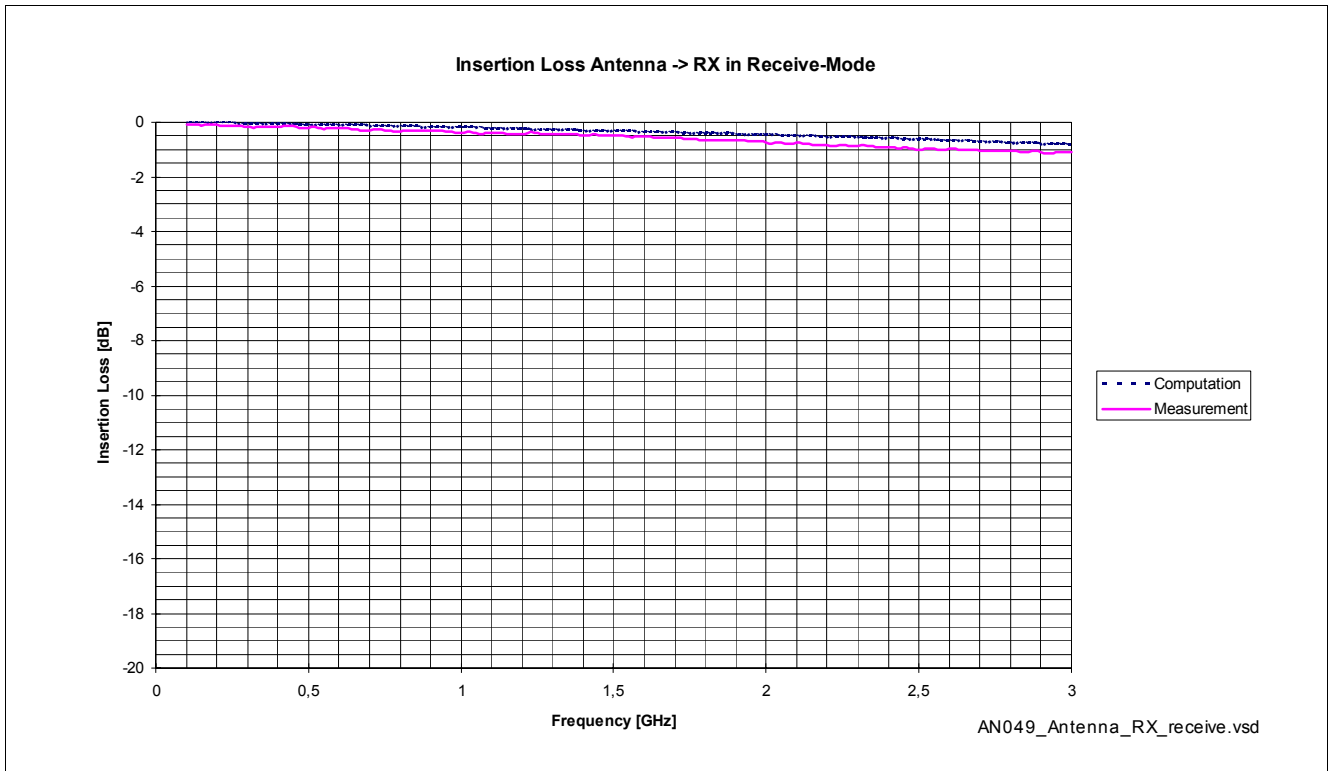


Figure 12 Insertion Loss Antenna → RX in Receive-Mode

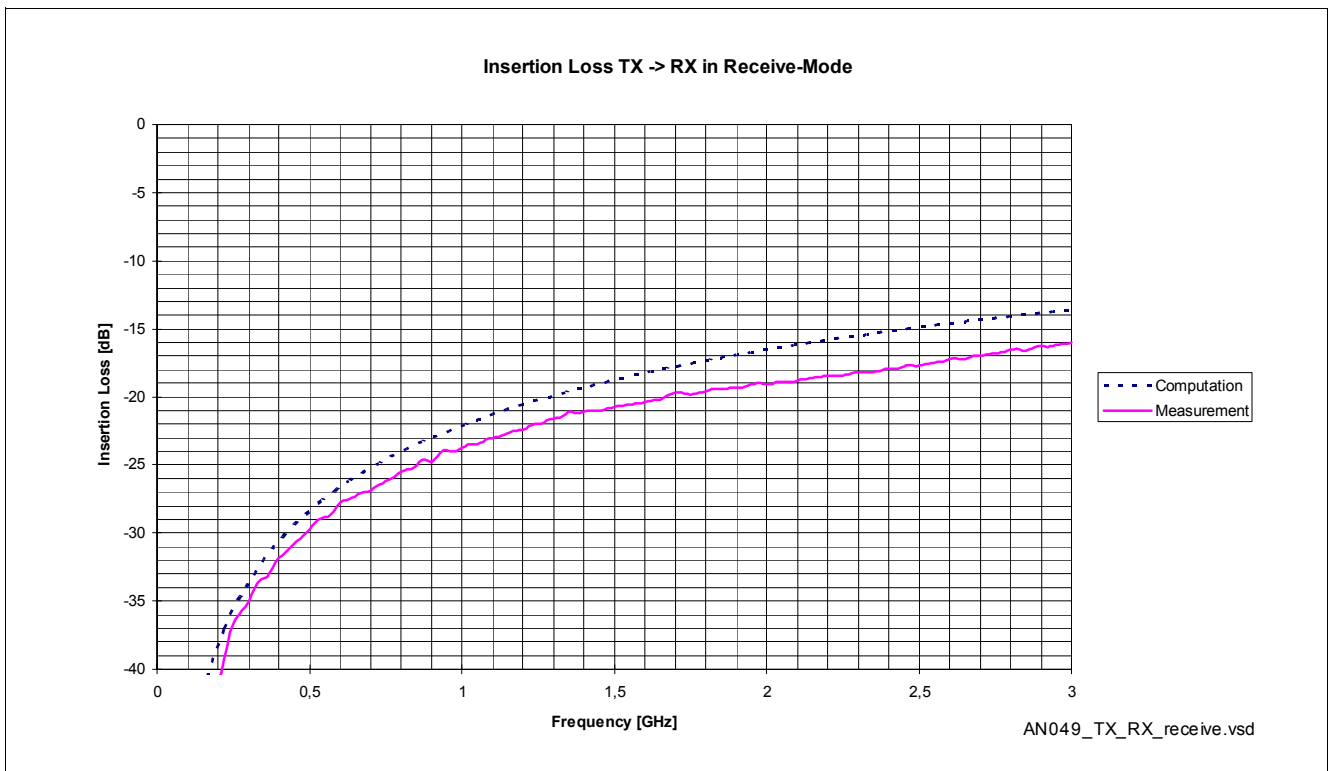


Figure 13 Insertion Loss TX → RX in Receive-Mode

The computed isolation parameters are worse than measured. This is due to the dielectric losses of the material, which seem to be lower than assumed for simulation.